

Driving decarbonization and digitalization. Together.



Engineer Process Integration

Job description

In your new role you will:

- Perform root cause analysis for ICO/FAR related defects, evaluate defect prevention methodologies in relevant unit processes
- Benchmark and perform interconnect-related process analysis for existing and new technologies to achieve maximum process capability against benchmark and work with UPS and BE engineering to eliminate defects and drive continuous improvement.
- Integration technical support in new technology transfer projects.
- Development of innovative processes and process characterization methodologies for existing and new interconnect technologies.
- Design & execute experiments and perform technical analysis & documentation on the results.
- Assessment of process changes and process change management
- Interface between business units, process engineering, frontend and backend sites, reliability engineering and production
- Interact and communicate effectively in cross functional teams e.g. in 8D teams and taskforces.

Profile

You are best equipped for this task if you have:

- PhD/Master/ Degree in Physics/Chemistry/Material Science/Mechanical Engineering/Electronics Engineering or equivalent
- At least 5 years of in-depth knowledge of characterization methodology on packaging assembly materials and processes
- Good knowledge in material science, metallurgy, polymer science, advanced failure analysis (fractures, intermetallic & microstructure, interfacial adhesion, surface & chemical analysis, outgassing, stress)
- Good technical knowledge in chip-to-package interactions with regards to interconnect reliability, materials and processes (wafer saw, die attach, wire bonding, flip chip bonding, molding. All-round expertise in FOL processes preferred)
- Good experience in problem solving methodologies and design of experiment.
- Good interpersonal skills, analytical and leadership skills & a good team player.
- Must be a self-starter who can work both independently and in groups across different site functional teams.

At a glance

Location: **Kulim (Malaysia)**
Job ID: **HRC0778779**
Start date: **May 20, 2024**
Entry level: **1-3 years**
Type: **Full time**
Contract: **Permanent**

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Job ID: **HRC0778779**
www.infineon.com/jobs



Benefits

- **Kulim:** Coaching, mentoring networking possibilities; Wide range of training offers & planning of career development; International assignments; Different career paths: Project Management, Technical Ladder, Management & Individual Contributor; Flexible working conditions; Holiday child care; Medical coverage; On-site social counselling and works doctor; Health promotion programs; On-site gym, jogging paths, beachvolleyball, tennis & soccer court; On-site canteen; Private insurance offers; Flexible transition into retirement

Why Us

Driving decarbonization and digitalization. Together.

Infineon designs, develops, manufactures, and markets a broad range of semiconductors and semiconductor-based solutions, focusing on key markets in the automotive, industrial, and consumer sectors. Its products range from standard components to special components for digital, analog, and mixed-signal applications to customer-specific solutions together with the appropriate software.

We are on a journey to create the best Infineon for everyone.

This means we embrace diversity and inclusion and welcome everyone for who they are. At Infineon, we offer a working environment characterized by trust, openness, respect and tolerance and are committed to give all applicants and employees equal opportunities. We base our recruiting decisions on the applicant's experience and skills.

Please let your recruiter know if they need to pay special attention to something in order to enable your participation in the interview process.

